

APPLICABLE STANDARD		SPECIFICATIONS			
RATING	OPERATING TEMPERATURE RANGE	-55 °C TO 85 °C ⁽¹⁾	STORAGE TEMPERATURE RANGE	-10 °C TO 60 °C ⁽²⁾	
	VOLTAGE	50 V AC	STORAGE HUMIDITY RANGE	RELATIVE HUMIDITY 85% max (NOT DEWED)	
	CURRENT	0.5 A	OPERATING HUMIDITY RANGE		
CONSTRUCTION		TEST METHOD	REQUIREMENTS	QT	AT
GENERAL EXAMINATION	VISUALLY AND BY MEASURING INSTRUMENT.		ACCORDING TO DRAWING.	x	x
MARKING	CONFIRMED VISUALLY.			x	x
ELECTRIC CHARACTERISTICS					
CONTACT RESISTANCE	100 mA(DC OR 1000Hz)		70 mΩ MAX.	x	—
INSULATION RESISTANCE	100 V DC.		100 MΩ MIN.	x	—
VOLTAGE PROOF	150 V AC FOR 1 min.		NO FLASHOVER OR BREAKDOWN.	x	x
MECHANICAL CHARACTERISTICS					
INSERTION AND WITHDRAWAL FORCES	MEASURED BY APPLICABLE CONNECTOR.		INSERTION FORCE: 84 N MAX. WITHDRAWAL FORCE: 10.3 N MIN.	x	—
MECHANICAL OPERATION	50 TIMES INSERTIONS AND EXTRACTIONS.		① CONTACT RESISTANCE: VARIATION FROM INITIAL VALUE 20 mΩ OR LESS. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x	—
VIBRATION	FREQUENCY 10 TO 55 TO 10Hz, APPROX 5min SINGLE AMPLITUDE : 0.75 mm, 10 CYCLES FOR 3 DIRECTIONS.		① NO ELECTRICAL DISCONTINUITY OF 1 μs. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x	—
SHOCK	490 m/s ² , DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.			x	—
ENVIRONMENTAL CHARACTERISTICS					
DAMP HEAT (STEADY STATE)	EXPOSED AT 40±2 °C, 90 ~ 95 %, 96 h.		① CONTACT RESISTANCE: VARIATION FROM INITIAL VALUE 20 mΩ OR LESS.	x	—
RAPID CHANGE OF TEMPERATURE	TEMPERATURE -55 → +85 °C TIME 30 → 30 min. UNDER 5 CYCLES. (RELOCATION TIME TO CHAMBER:WITHIN 2~3 MIN)		② INSULATION RESISTANCE :100 MΩ MIN. ③ NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x	—
COLD	EXPOSED AT -55°C, 96 h		① CONTACT RESISTANCE: VARIATION FROM INITIAL VALUE 20 mΩ OR LESS.	x	—
DRY HEAT	EXPOSED AT 85°C, 96 h		② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x	—
SULFUR DIOXIDE	EXPOSED AT 25±2°C, 75±5%RH, 25 PPM FOR 96 h. (TEST STANDARD: JIS C 60068)		① NO DEFECT SUCH AS CORROSION WHICH IMPAIRS THE FUNCTION OF CONNECTOR. ② CONTACT RESISTANCE: VARIATION FROM INITIAL VALUE 20 mΩ OR LESS.	x	—
RESISTANCE TO SOLDERING HEAT	1)REFLOW SOLDERING : PEAK TMP : 260°C MAX REFLOW TMP: 220°C MIN FOR 60sec 2) SOLDERING IRONS : 360°C MAX. FOR 5 sec.		NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINAL.	x	—
SOLDERABILITY	SOLDERED AT SOLDER TEMPERATURE 240±3°C FOR IMMERSION DURATION, 3 sec.		A NEW UNIFORM COATING OF SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.	x	—
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
	4	DIS-F-005857	KT. DOI	KI. HIROKAWA	11.11.24
REMARKS ⁽¹⁾ INCLUDE TEMPERATURE RISE CAUSED BY CURRENT-CARRYING. ⁽²⁾ "STORAGE" MEANS A LONG-TERM STORAGE STATE FOR THE UNUSED PRODUCT BEFORE ASSEMBLY TO PCB.				APPROVED	HS. OKAWA
				CHECKED	KI. HIROKAWA
				DESIGNED	KT. DOI
				DRAWN	KT. DOI
Unless otherwise specified, refer to JIS-C-5402.					
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWING NO.	ELC4-336342-00	
		SPECIFICATION SHEET	PART NO.	FX20-120S-0.5SV	
		HIROSE ELECTRIC CO., LTD.	CODE NO.	CL570-1105-6-00	1/1